



**ProsPower**

**PS06N20DA**

**20V Dual Channel NMOSFET**

Revision : 1.0  
Update Date : Apr. 2011

**ProsPower Microelectronics Co., Ltd**

### 1. General Description

The PS06N20DA uses advanced trench technology and design to provide excellent  $R_{ds(on)}$  with low gate charge. This device is suitable for use in high efficiency switching applications, DC/DC conversion, CPU power delivery and Synchronous rectification. Standard Product PS06N20DA is Pb-free (meets ROHS & Sony 259 specifications). It is offered in the very popular SOT23-6 package

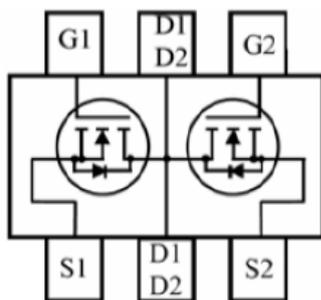
### 2. Applications

- Battery management
- Power management
- DC-DC converter
- Load switch
- LCD adapter

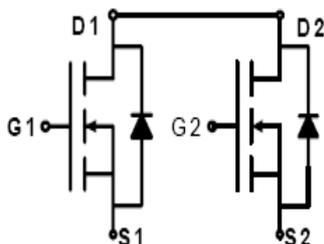
### 3. Features

- $V_{ds}=20V, I_d=6A$
- $R_{ds(on)} < 23\text{mohm}$  ( $V_{gs}=4.5V$ )
- Low capacitance minimizes driver loss
- Optimized gate charge minimizes switching loss

### Pin Configuration



SOT23-6



Schematic

### Pin Descriptions

Pin Name	Symbol	Function
Gate(4,6)	G1/G2	Device Gate terminal
Drain(2,5)	D1/D2	Device drain terminal
Source(1,3)	S1/S2	Device source terminal

**Absolute Maximum Ratings**

Stress greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These stress ratings only, and functional operation of the device at these or any conditions beyond those indicated under recommended Operating Conditions is not implied. Exposure to “Absolute Maximum Rating” for extended periods may affect device reliability. Use of standard ESD handling precautions is required..

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		$V_{DS}$	20	V
Gate-Source Voltage		$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$T_C=25^\circ\text{C}$ (Note 3)	$I_D$	6	A
Power Dissipation	$T_C=25^\circ\text{C}$	$P_D$	0.5	W
Junction and Storage Temperature Range		$T_J, T_{STG}$	-65 to 150	$^\circ\text{C}$

**Electrical Specifications**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
<b>STATIC PARAMETERS</b>						
Drain-Source Breakdown Voltage	$BVD_{SS}$	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20	22		V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$ $T_J=25^\circ\text{C}$			1	$\mu\text{A}$
Gate-Body leakage current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			0.1	$\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5	0.72	1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{V}, I_D=6\text{A}$		22	23	m $\Omega$
		$V_{GS}=2.5\text{V}, I_D=4\text{A}$		31	35	
Forward Transconductance	$g_{FS}$	$V_{DS}=5\text{V}, I_D=4.5\text{A}$		10		S
Body-Diode Continuous Current	$I_S$				1.7	A
Diode Forward Voltage	$V_{SD}$	$I_S=1.5\text{A}, V_{GS}=0\text{V}$		0.8	1	V
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=8\text{V}, f=1\text{MHz}$		600		pF
Output Capacitance	$C_{oss}$			330		pF
Reverse Transfer Capacitance	$C_{rss}$			140		pF
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge	$Q_g$	$V_{GS}=4.5\text{V}, V_{DD}=10\text{V}, I_D=6\text{A}$ (Note 2)		10	15	nC
Gate Source Charge	$Q_{gs}$			2.3		nC
Gate Drain Charge	$Q_{gd}$			2.9		nC
Turn-On Delay Time	$t_{D(on)}$	$I_D=1\text{A}, V_{DD}=10\text{V}, V_{GEN}=4.5\text{V}, R_L=10\Omega$		8	20	ns
Turn-On Rise Time	$t_r$			10	25	ns

Turn-Off Delay Time	$t_{D(off)}$	$R_G=6\Omega$ (Note 2)		35	70	ns
Turn-Off Fall Time	$t_f$			30	60	ns

**Notes**

1. Pulse width limited by max. junction temperature
2. Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board,  $t \leq 5\text{sec}$ ; 180°C/W when mounted on min. copper pad.



Typical Performance Characteristics

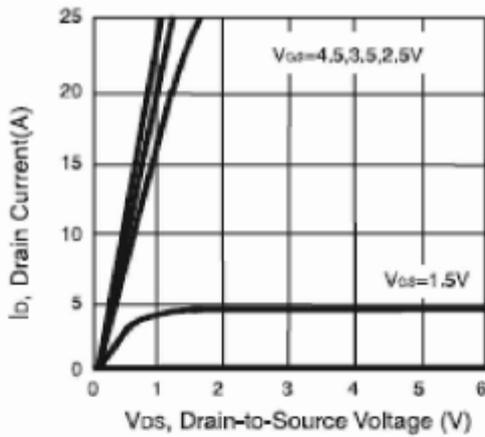


Figure 1. Output Characteristics

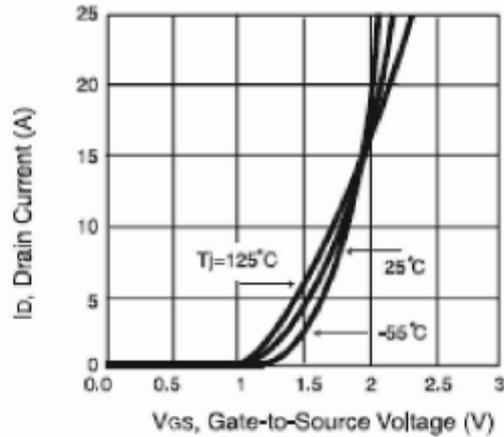


Figure 2. Transfer Characteristics

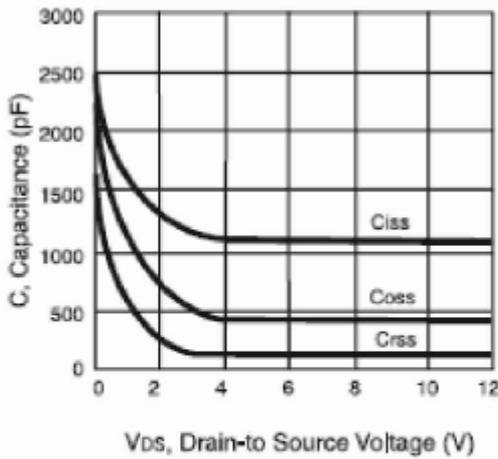


Figure 3. Capacitance

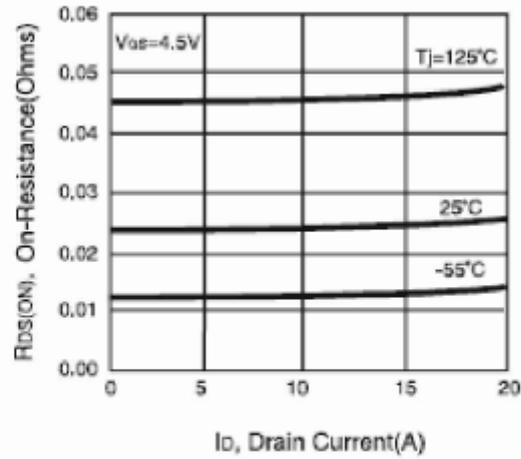


Figure 4. On-Resistance Variation with Drain Current and Temperature

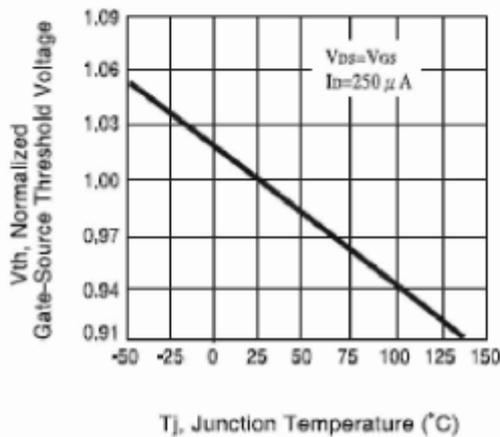


Figure 5. Gate Threshold Variation with Temperature

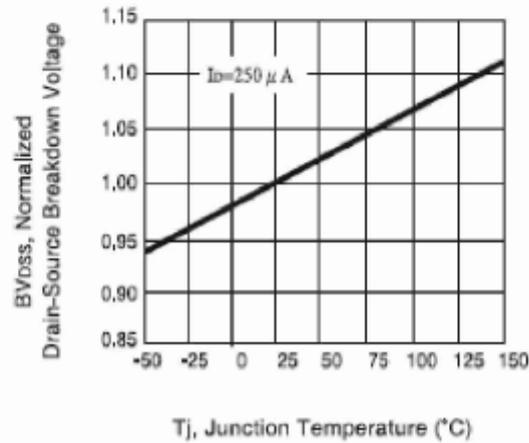


Figure 6. Breakdown Voltage Variation with Temperature

Typical Performance Characteristics (contd.)

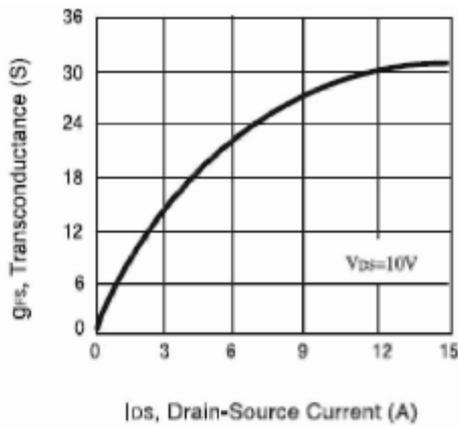


Figure 7. Transconductance Variation with Drain Current

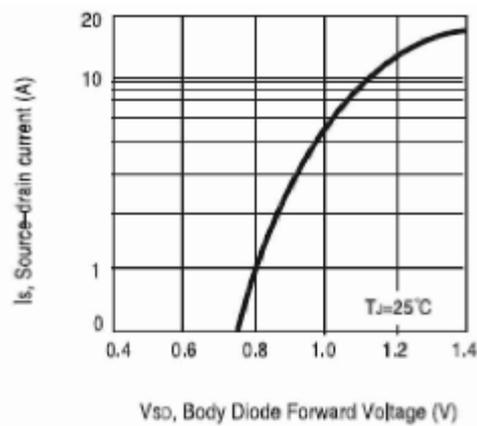


Figure 8. Body Diode Forward Voltage Variation with Source Current

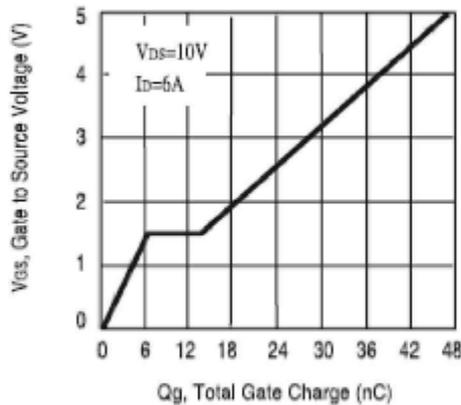


Figure 9. Gate Charge

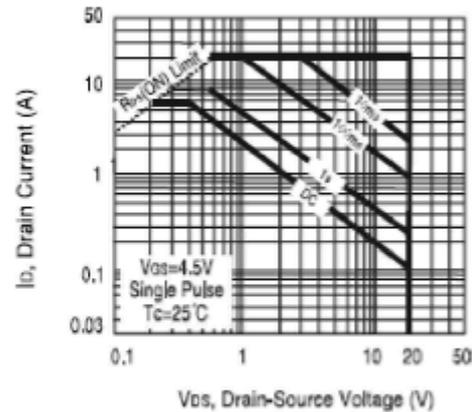


Figure 10. Maximum Safe Operating Area

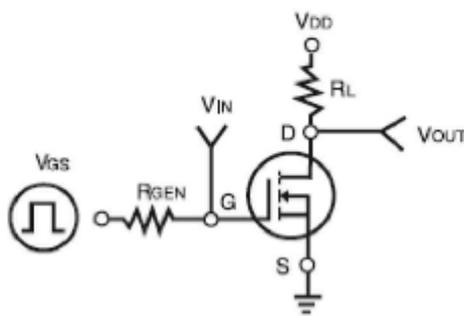


Figure 11. Switching Test Circuit

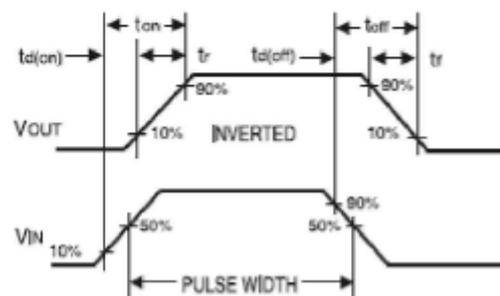
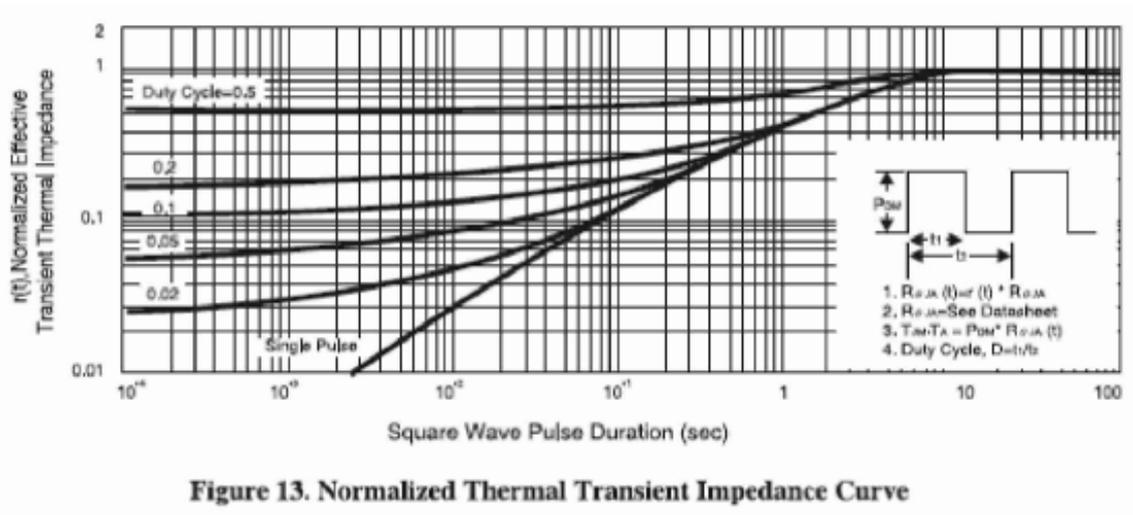


Figure 12. Switching Waveforms

Typical Performance Characteristics (contd.)





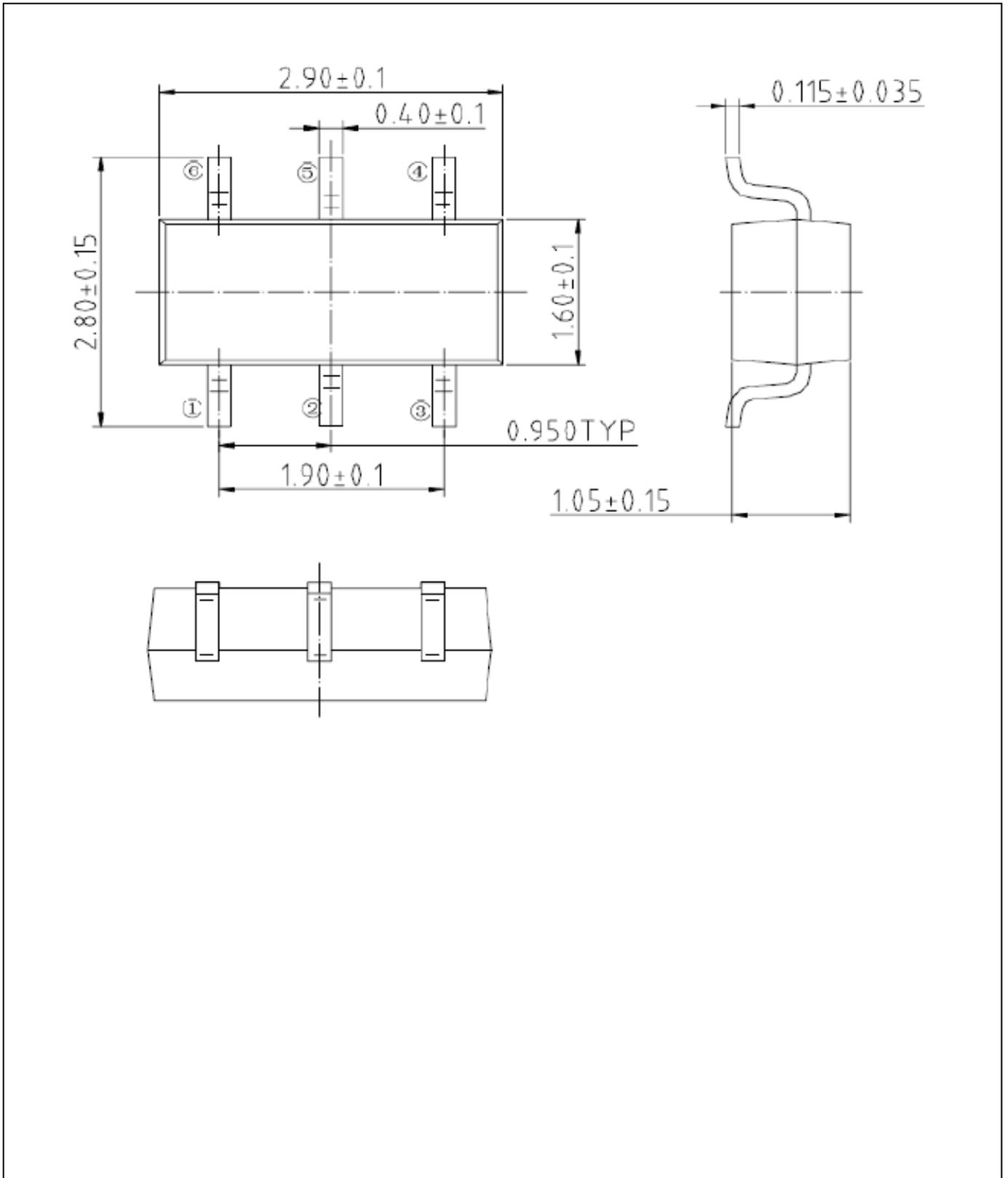
ProsPower

PS06N20DA

20V Dual Channel NMOSFET

Package Dimensions

SOT23-6



**Ordering Information**

Device	Operating T <sub>j</sub>	PKG Type	Wrap	Order Number
PS06N20DA	-65C° ≤ 150C°	SOT23-6	T&R	PS06N20DA-M6-TL

Note: Lead Free and RoHS compliant.

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